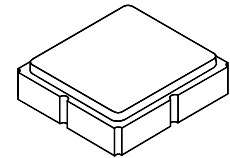


SF2166E

1280.18 MHz



SM3030-8

- **SAW Filter for Digital Television**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Meets AEC-Q200 Standards**



Characteristics:

Balance-to-balanced operation

Terminating source/load impedance : $Z_S = 150 \Omega$

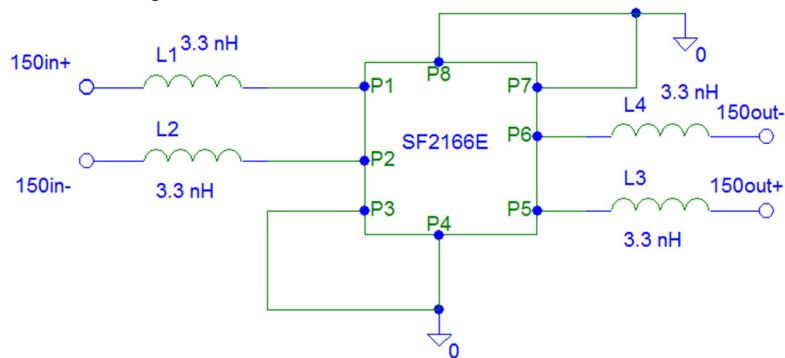
Maximum Rating

Rating	Value	Units
Input Power Level	+10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range	-50 to +95	°C
Maximum Soldering Profile, 5 cycles/ 10 seconds maximum	265	°C

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			1280.18		MHz
Insertion Loss, 1260.18 to 1300.18 MHz	IL			3.2	4.5	dB
Amplitude Ripple, 1260.18 to 1300.18 MHz				1.0	2.3	dB
Group Delay Ripple, 1260.18 to 1300.18 MHz				20	30	ns _{p-p}
Attenuation, 0 dB Reference:						
100 to 1198.12 MHz			47	50		dB
1362.24 to 2000 MHz			45	55		
2000 to 6000 MHz			30	40		

Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	858, YWWS					
Standard Reel Quantity	Reel Size 7 inch					500 Pieces/Reel
	Reel Size 13 inch					3000 Pieces/Reel

Tuning Network, 150 ohm Balanced Source/Load

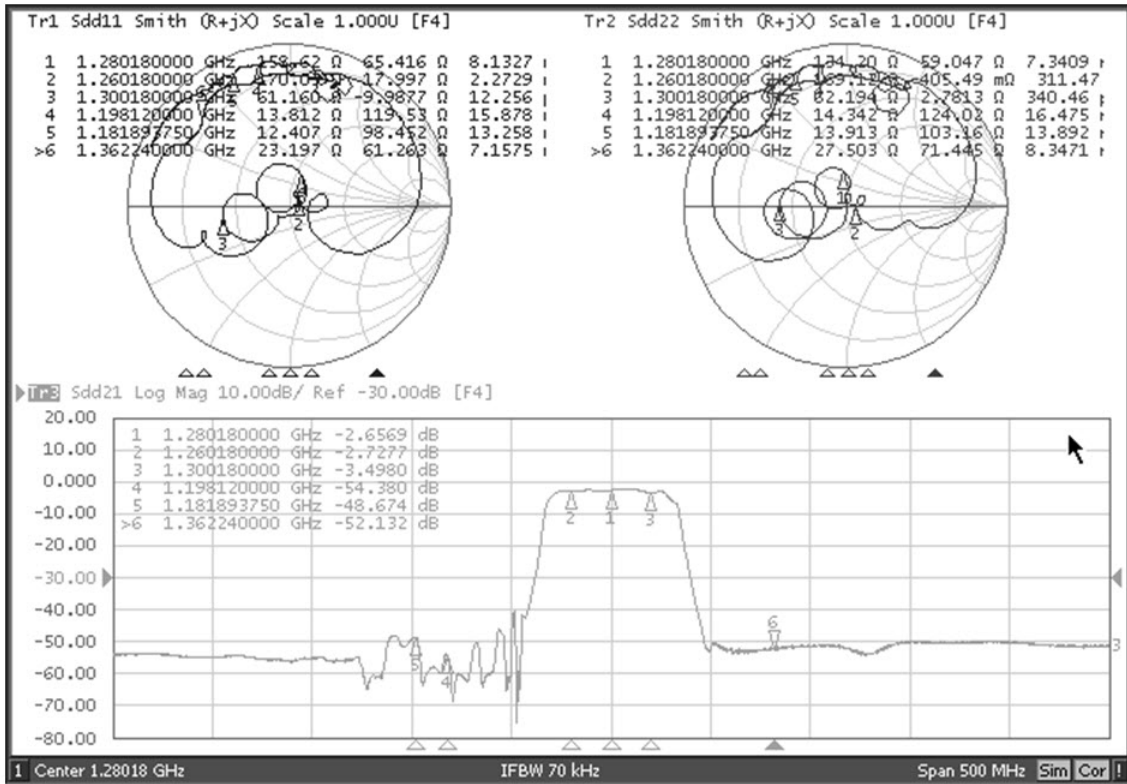


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

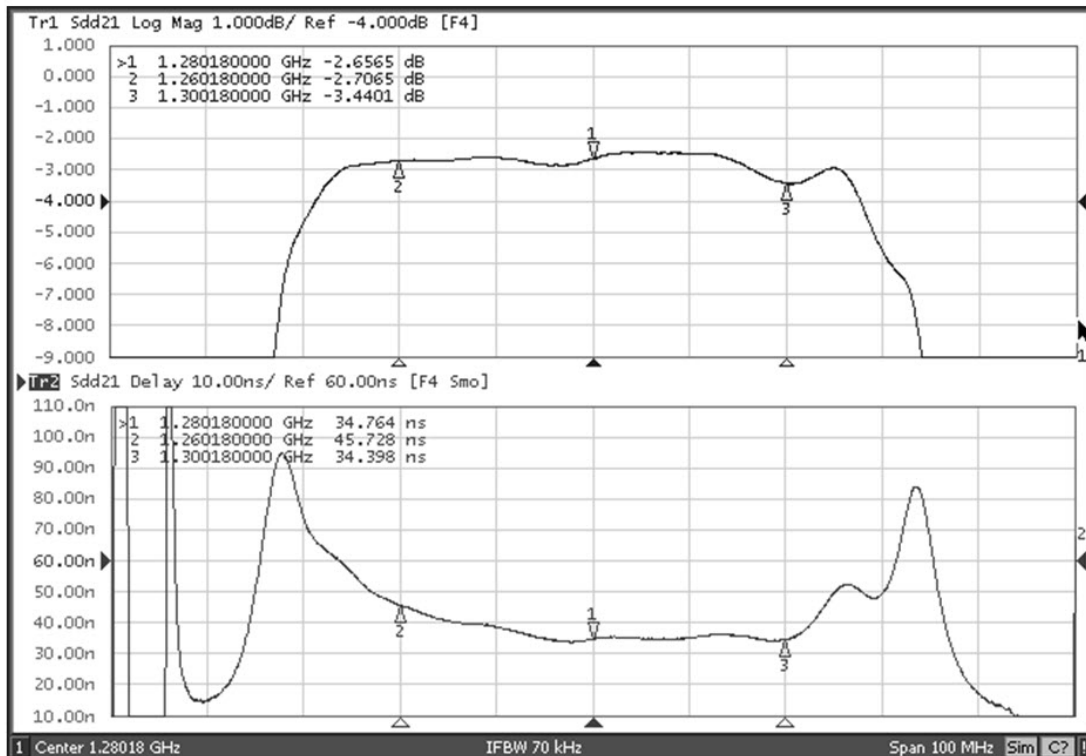
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

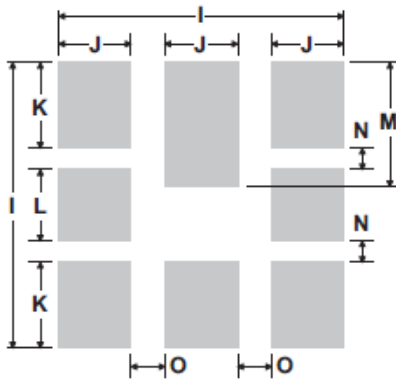
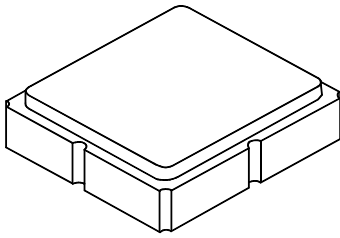
Filter S21, S11 and S22 Plots



Filter Passband and Group Delay Plot



8-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

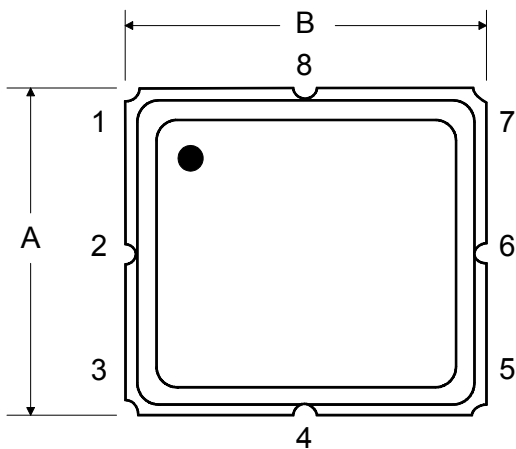
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.0	3.13	0.113	0.118	0.123
B	2.87	3.0	3.13	0.113	0.118	0.123
C	1.14	1.27	1.40	0.045	0.050	0.055
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I	-	3.19	-	-	0.126	-
J	-	0.81	-	-	0.032	-
K	-	0.96	-	-	0.038	-
L	-	0.81	-	-	0.032	-
M	-	1.39	-	-	0.055	-
N	-	0.23	-	-	0.009	-
O	-	0.38	-	-	0.015	-

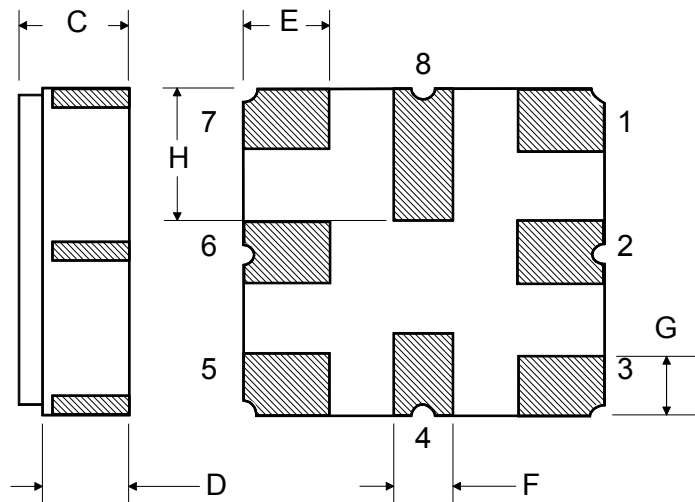
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

TOP VIEW



BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

